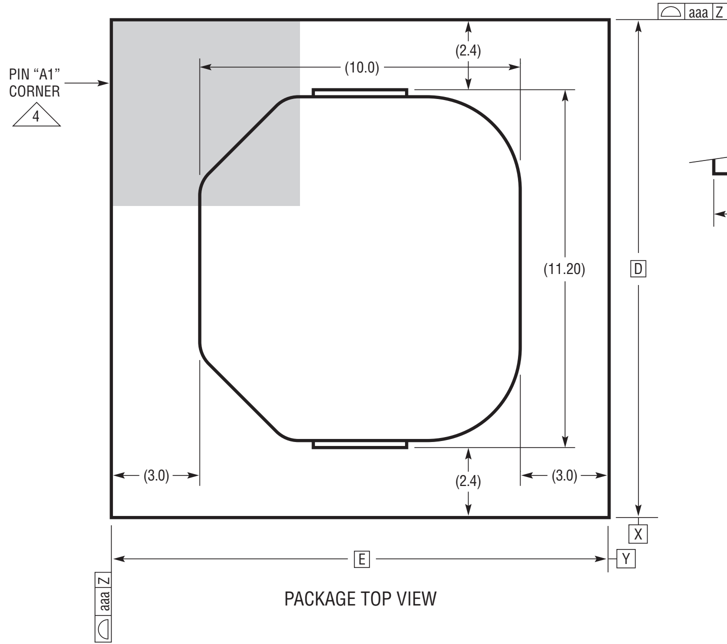
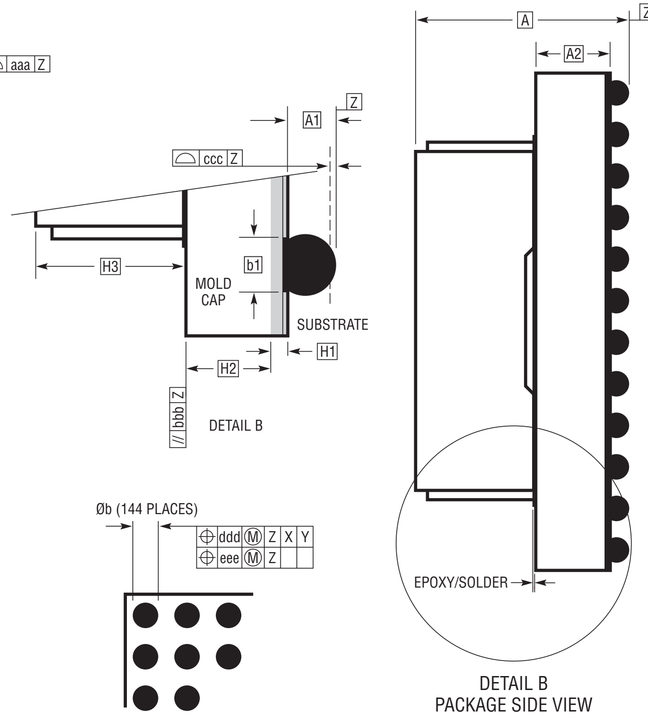
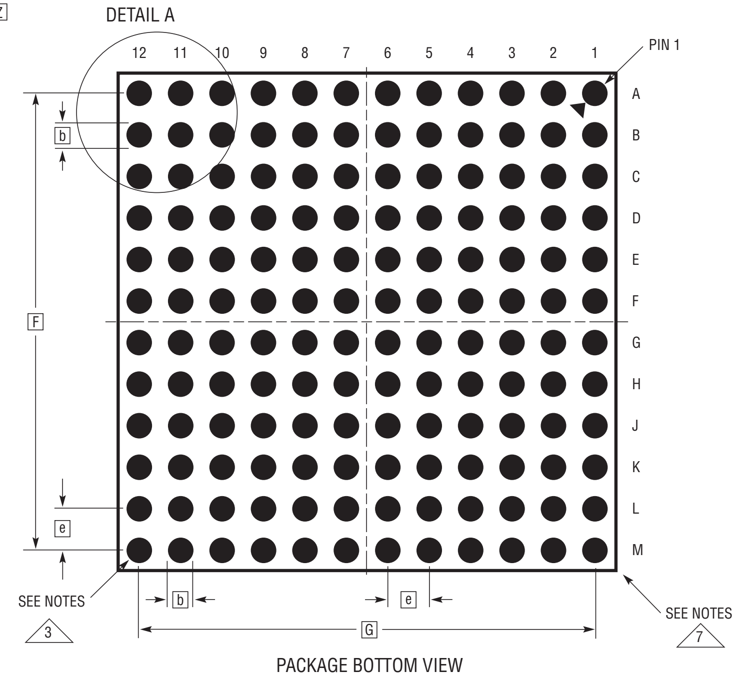
# BGA Package
## 144-Lead (16mm × 16mm × 7.07mm)
(Reference LTC DWG # 05-08-1937 Rev D)



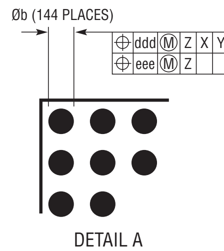

PACKAGE TOP VIEW



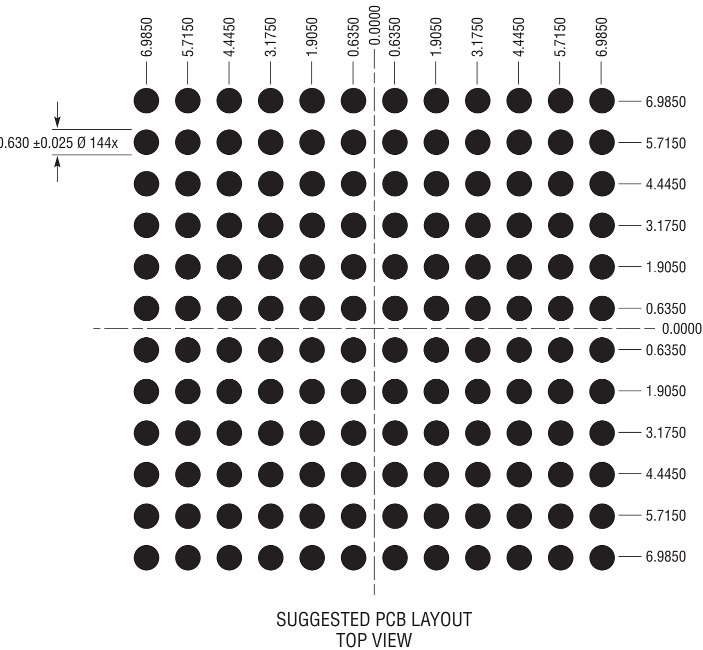

DETAIL B
PACKAGE SIDE VIEW




PACKAGE BOTTOM VIEW



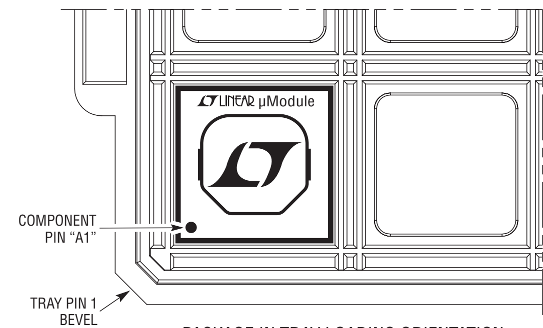

DETAIL A




SUGGESTED PCB LAYOUT
TOP VIEW

| DIMENSIONS | | | | |
|---|---|---|---|---|
| SYMBOL | MIN | NOM | MAX | NOTES |
| A | 6.57 | 7.07 | 7.42 | |
| A1 | 0.50 | 0.60 | 0.70 | BALL HT |
| A2 | 2.31 | 2.41 | 2.51 | |
| b | 0.60 | 0.75 | 0.90 | BALL DIMENSION |
| b1 | 0.60 | 0.63 | 0.66 | PAD DIMENSION |
| D | | 16.00 | | |
| E | | 16.00 | | |
| e | | 1.27 | | |
| F | | 13.97 | | |
| G | | 13.97 | | |
| H1 | 0.36 | 0.41 | 0.46 | SUBSTRATE THK |
| H2 | 1.95 | 2.00 | 2.05 | MOLD CAP HT |
| H3 | 3.76 | 4.06 | 4.21 | INDUCTOR HT |
| aaa | | | 0.15 | |
| bbb | | | 0.10 | |
| ccc | | | 0.20 | |
| ddd | | | 0.30 | |
| eee | | | 0.15 | |
| TOTAL NUMBER OF BALLS: 144 | | | | |

NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994
2. ALL DIMENSIONS ARE IN MILLIMETERS. DRAWING NOT TO SCALE
3. BALL DESIGNATION PER JEP95
4. DETAILS OF PIN #1 IDENTIFIER ARE OPTIONAL, BUT MUST BE LOCATED WITHIN THE ZONE INDICATED. THE PIN #1 IDENTIFIER MAY BE EITHER A MOLD OR MARKED FEATURE
5. PRIMARY DATUM -Z- IS SEATING PLANE
6. SOLDER BALL COMPOSITION CAN BE 96.5% Sn/3.0% Ag/0.5% Cu OR Sn Pb EUTECTIC
7. ⚠ PACKAGE ROW AND COLUMN LABELING MAY VARY AMONG μModule PRODUCTS. REVIEW EACH PACKAGE LAYOUT CAREFULLY




PACKAGE IN TRAY LOADING ORIENTATION

BGA 144 1016 REV D